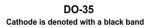




1N/FDLL 914/A/B / 916/A/B / 4148 / 4448 **Small Signal Diode**







THE PLACEMENT OF THE EXPANSION GAP HAS NO RELATIONSHIP TO THE LOCATION OF THE CATHODE TERMINAL

LL-34 COLOR BAND MARKING				
DEVICE	1ST BAND	2ND BAND		
FDLL914	BLACK	BROWN		
FDLL914A	BLACK	GRAY		
FDLL914B	BROWN	BLACK		
FDLL916	BLACK	RED		
FDLL916A	BLACK	WHITE		
FDLL916B	BROWN	BROWN		

-1st band denotes cathode terminal and has wider width

BLACK BROWN

BROWN

BLACK

FDLL4148 FDLL4448

Absolute Maximum Ratings* Ta=25°C unless otherwise noted

Symbol	Parameter	Value	Units
V _{RRM}	Maximum Repetitive Reverse Voltage	100	V
I _O	Average Rectified Forward Current	200	mA
I _F	DC Forward Current	300	mA
i _f	Recurrent Peak Forward Current	400	mA
I _{FSM}	Non-repetitive Peak Forward Surge Current Pulse Width = 1.0 second 1.0 A Pulse Width = 1.0 microsecond 4.0 A		l
T _{STG}	Storage Temperature Range	-65 to + 175	°C
TJ	Operating Junction Tempera	-65 to + 175	°C

^{*} These ratings are limiting values above which the serviceability of the diode may be impaired.

Thermal Characteristics

Symbol	Parameter	Max.	Units	
Cymbol	i didilictei	1N/FDLL 914/A/B / 4148 / 4448		
P_{D}	Power Dissipation	500	mW	
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient	300	°C/W	

These ratings are based on a maximum junction temperature of 200 degrees C.
 These are steady state limits. The factory should be consulted on applications involving pulsed or low duty cycle operations.

Symbol	Parameter	Test Conditions	Min.	Max.	Units
V _R	Breakdown Voltage	I _R = 100μA I _R = 5.0μA	100 75		V V
V _F	Forward Voltage 1N914B/4448 1N916B 1N914/916/4148 1N914A/916A 1N916B 1N914B/4448	I _F = 5.0mA I _F = 10mA I _F = 20mA I _F = 20mA	620 630	720 730 1.0 1.0 1.0	mV mV V V
I _R	Reverse Leakage	V _R = 20V V _R = 20V, T _A = 150°C V _R = 75V		25 50 5.0	nA μA μA
СТ	Total Capacitance 1N916A/B/4448 1N914A/B/4148	V _R = 0, f = 1.0MHz V _R = 0, f = 1.0MHz		2.0 4.0	pF pF
t _{rr}	Reverse Recovery Time	$I_F = 10$ mA, $V_R = 6.0$ V (600mA) $I_{rr} = 1.0$ mA, $R_L = 100$ Ω		4.0	ns

^{*} Non-recurrent square wave PW = 8.3ms

Typical Characteristics

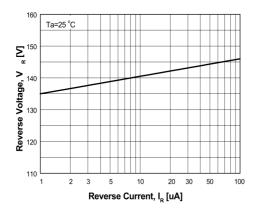


Figure 1. Reverse Voltage vs Reverse Current BV - 1.0 to $100\mu A$

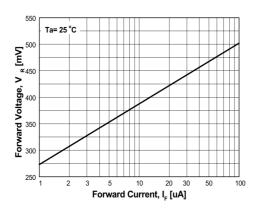
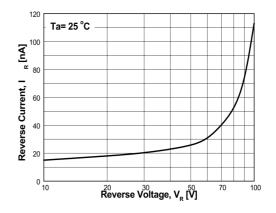


Figure 3. Forward Voltage vs Forward Current VF - 1 to $100 \mu \text{A}$



GENERAL RULE: The Reverse Current of a diode will approximately double for every ten (10) Degree C increase in Temperature

Figure 2. Reverse Current vs Reverse Voltage IR - 10 to 100V

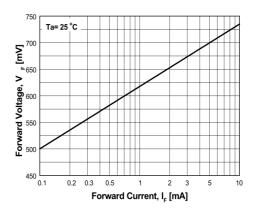


Figure 4. Forward Voltage vs Forward Current VF - 0.1 to 10mA

Typical Characteristics (Continued)

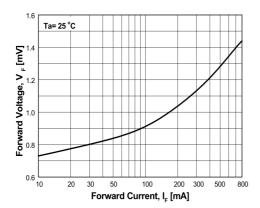
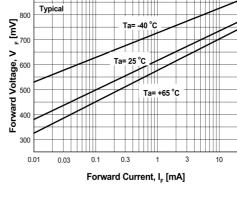


Figure 5. Forward Voltage vs Forward Current VF - 10 to 800mA



900

Figure 6. Forward Voltage vs Ambient Temperature VF - 0.01 - 20 mA (- 40 to +65°C)

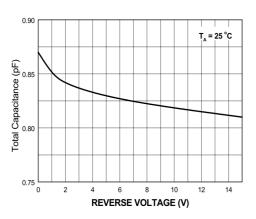
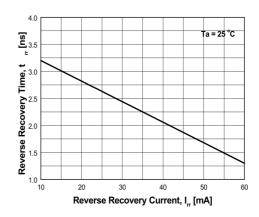


Figure 7. Total Capacitance



IF = 10mA, IRR = 1.0 mA, Rloop = 100 Ohms
Figure 8. Reverse Recovery Time vs
Reverse Recovery Current

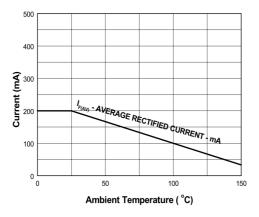


Figure 9. Average Rectified Current $(I_{F(AV)})$ vs Ambient Temperature (T_A)

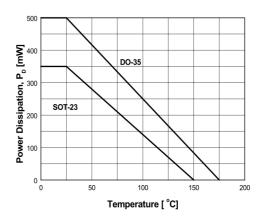


Figure 10. Power Derating Curve

UniFET™ VCX™ Wire™



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MSX™	RapidConfigure™	TinyLogic [®]
MSXPro™	RapidConnect™	TINYOPTO™
Across the board. Around the world.™		TruTranslation™
	ScalarPump™	UHC [®]
	GTOTM HiSeCTM I ² CTM i-LoTM ImpliedDisconnectTM IntelliMAXTM ISOPLANARTM LittleFETTM MICROCOUPLERTM MicroFETTM MicroPakTM MICROWIRETM MSXTM MSXPTOTM	GlobalOptoisolator™ GTO™ GTO™ HiSeC™ PACMAN™ POP™ InpliedDisconnect™ IntelliMAX™ ISOPLANAR™ Power247™ Power247™ PowerEdge™ ISOPLANAR™ PowerSaver™ LittleFET™ MICROCOUPLER™ MicroPak™ MicroPak™ MICROWIRE™ MSX™ MSXPro™ RapidConnect™

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